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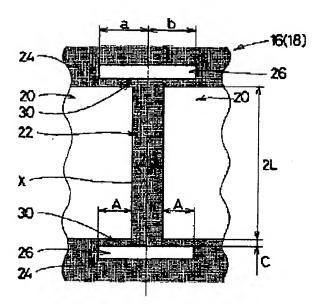
TITLE

ELECTRODE FORMING METHOD OF

ELECTRONIC PARTS AND

ELECTRODE FORMING DEVICE USED

FOR THE SAME



ABSTRACT :

PROBLEM TO BE SOLVED: To provide an electrode forming method of electronic parts which have the extremely few electrode pattern defects occurring in thermal deformation and are less degraded in strength, and an electrode forming device.

SOLUTION: This electrode forming device for the electronic parts includes a film forming pattern mask 16 having film forming holes 20 and masking parts 22. This film forming pattern mask 16 is provided with relief holes 26 of, for example, a rectangular shape on both sides in the longitudinal direction of the masking parts 22, by which flexible parts 30 like, for example, fixed beams, fixed at their both ends as fixing ends are formed between the masking parts 22 and these relief holes 26. The thermal stresses in the masking parts 22 occurring in the temp. difference between the masking parts 22 and their peripheral parts at the time of the film forming treatment are absorbed by the flexible parts 30 which deflect toward the relieve holes 26.

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